

SCHOTTKY BARRIER DIODES FOR GENERAL PURPOSE APPLICATIONS

5082-2301/02/03/05 5082-2800(1N5711) 5082-2810(1N5712) 5082-2811(1N5713) 5082-2815 5082-2900

HSCH-1001(1N6263)

Features

LOW TURN-ON VOLTAGE: .34V AT 1mA PICO-SECOND SWITCHING SPEED HIGH BREAKDOWN VOLTAGE: UP TO 70V UNIFORM FORWARD TRACKING

Description/Applications

The 5082-2800, 2810, 2811 are passivated Schottky barrier diodes which use a patented "guard ring" design to achieve a high breakdown voltage. They are packaged in a low cost glass package. They are well suited for high level detecting, mixing, switching, gating, log or A-D converting, video detecting, frequency discriminating, sampling and wave shaping.

The 5082-2835 is a passivated Schottky diode in a low cost glass package. It is optimized for low turn-on voltage. The 5082-2835 is particularly well suited for UHF mixing.

The 5082-2300 and 2900 Series devices are unpassivated Schottky diodes in a glass package. These diodes have extremely low 1/f noise and are ideal for low noise mixing, and high sensitivity detecting. They are particularly well suited for use in Doppler or narrow band video receivers.

The HSCH-1001 is a Hybrid Schottky diode sealed in a rugged double stud Outline 12 glass package suitable for automatic insertion. The low turn-on voltage, fast switching speed, and low cost of these diodes make them ideal for general purpose switching.

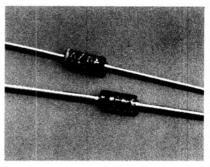
Application Bulletins 13, 14, 15, and 16 describe applications in which these diodes are used for speed up of a transistor, clipping, clamping, and sampling, respectively.

Maximum Ratings at T_{CASE}=25°C

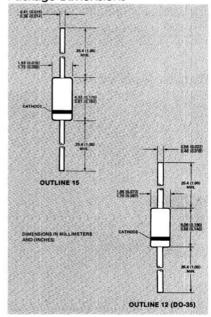
Junction Operating and Storage Temperature Range 5082-2305, 2301, 2302, 2303, 2900 . -660°C to +125°C 5082-2800, 2810, 2811, HSCH-1001 . -65°C to +200°C 5082-2835 -60°C to +150°C

Operation of these devices within the above temperature ratings will assure a device Mean Time Between Failure (MTBF) of approximately 1 x 107 hours.

DC Power Dissipation (Measured in an infinite heat sink)
Derate linearly to zero at maximum rated temperature
5082-2305, 2301, 2302, 2303, 2900 ... 125 mW
5082-2800, 2810, 2811 ... 250 mW
5082-2835 ... 150 mW
HSCH-1001 ... 400 mW
Peak Inverse Voltage ... Van



Package Dimensions



Electrical Specifications at T_A=25°C

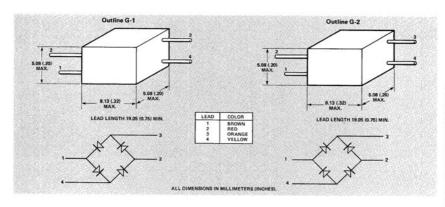
Part Number 5082-	Package Outline	Minimum Breakdown Voltage V _{BR} (V)	Maximum Forward Voltage V _F (mV)	V _F =1V Max at Forward Current I _F (mA)	Maximum Reverse Leakage Current IR (nA) at VR (V)		Maximum Capacitance C _T (pF)
2800	15	70	410	15	200	50	2.0
1N5711[1]	15	70	410	15	200	50	2.0
2305	15	30	400	75	300	15	1.0
2301[2]	15	30	400	50	300	15	1.0
2302[2]	15	30	400	35	300	15	1.0
2303[2]	15	20	400	35	500	15	1.0
2810	15	20	410	35	100	15	1.2
1N5712[1]	15	20	550	35	150	16	1.2
2811	15	15	410	20	100	8	1.2
1N5713[1]	15	15	410	20	100	8	1.2
2900	15	10	400	20	100	5	1.2
2835	15	5*	340	10†	100	1	1.0
HSCH-1001[1] (1N6263)	12 (DO-35)	60	410	15	200	50	2.2
Test Conditions		I _R = 10 μA *I _R = 100 μA	I _F = 1 mA	†V _F = .45V			V _R = 0 V f = 1.0 MHz

Notes:

Matched Pairs and Quads

Basic Part Number 5082-	Matched Pair Unconnected	Matched Quad Unconnected	Matched Ring Quad Encapsulated G-1 Outline	Matched Bridge Quad Encapsulated G-2 Outline	Batch Matched	Test Conditions
2301	5082-2306 ΔV _F = 20 mV ΔCo = 0.2 pF					ΔV _F at I _F = 0.75-20 mA ΔCo at f = 1.0 MHz
2303	5082-2308 ΔV _F = 20 mV ΔCo = 0.2 pF	5082-2370 ΔV _F = 20 mV ΔCo = 0.2 pF	5082-2396 ΔV _F = 20 mV ΔCo = 0.2 pF	5082-2356 ΔV _F = 20 mV ΔCo = 0.2 pF		ΔV _F at I _F = 0.75–20 mA ΔCo at f = 1.0 MHz
2900	5082-2912 ΔV _F = 30 mV	5082-2970 ΔV _F = 30 mV	5082-2996 ΔV _F = 30 mV	5082-2997 ΔV _F = 30 mV		ΔV _F at I _F = 1.0 – 10 mA
2800	5082-2804 ΔV _F = 20 mV	5082-2805 ΔV _F = 20 mV			5082-2836 ΔV _F = 20 mV ΔC _O = 0.1 pF	ΔV_F at I_F = 0.5 -5 mA ΔC_O at f = 1.0 MHz
2811		5082-2815 ΔV _F = 20 mV	5082-2814 ΔV _F = 20 mV	5082-2813 ΔV _F = 20 mV	5082-2826 ΔV _F = 10 mV ΔC _O = 0.1 pF	ΔV_F at $I_F = 10$ mA ΔC_O at $f = 1.0$ MHz
2835					$5082-2080$ $\Delta V_F = 10 \text{ mV}$ $\Delta C_O = 0.1 \text{ pF}$	ΔV_F at I_F = 10 mA ΔC_O at f = 1.0 MHz

^{1.} Effective Minority Carrier Lifetime (r) for all these diodes is 100 ps maximum measured with Krakauer method at 20 mA except for HSCH-1001 (1N6263), 1N5711, 1N5712, and 1N5713 which are measured at 5 mA. 2. 5082-2301 = 1N5165, 5082-2302 = 1N5166, 5082-2303 = 1N5167.



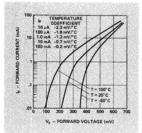


Figure 1. I-V Curve Showing Typical Temperature Variation for 5082-2300 Series Schottky Diodes.

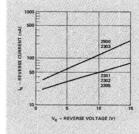


Figure 2. 5082-2300 and 5082-2900 Series Typical Reverse Current vs. Reverse Voltage at T_A = 25°C.

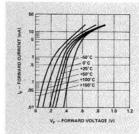


Figure 3, I-V Curve Showing Typical Temperature Variation for 5082-2800 or 1N5711 Schottky Diodes.

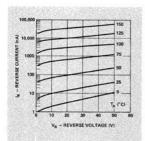


Figure 4. (5082-2800 or 1N5711) Typical Variation of Reverse Current (I_R) vs. Reverse Voltage (V_R) at Various Temperatures.

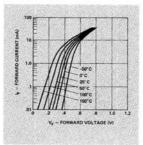


Figure 5. I-V Curve Showing Typical Temperature Variation for the 5082-2810 or 1N5712 Schottky Diode.

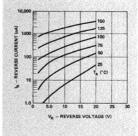


Figure 6. (5082-2810 or 1N5712) Typical Variation of Reverse Current (IR) vs. Reverse Voltage (VR) at Various Temperatures.

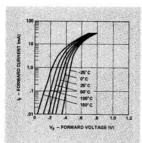


Figure 7. I-V Curve Showing Typical Temperature Variation for 5082-2811 Schottky Diode.

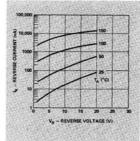


Figure 8. (5082-2811) Typical Variation of Reverse Current (IR) vs. Reverse Voltage (VR) at Various Temperatures.

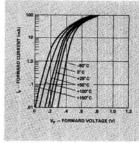


Figure 9. I-V Curve Showing Typical Temperature Variations for 5082-2835 Schottky Diode.

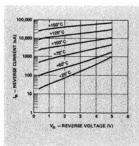


Figure 10. (5082-2835) Typical Variation of Reverse Current (I_R) vs. Reverse Voltage (V_R) at Various Temperatures.

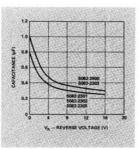


Figure 11. 5082-2300 and -2900 Series Typical Capacitance vs. Reverse Voltage.

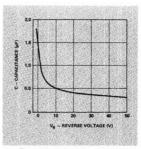


Figure 12. (5082-2800 or 1N5711) Typical Capacitance (C) vs Reverse Voltage (VR).

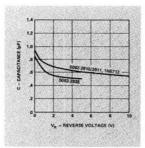


Figure 13. Typical Capacitance (C) vs. Reverse Voltage (V_R).

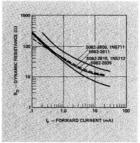


Figure 14. Typical Dynamic Resistance (R_D) vs. Forward Current (I_F).

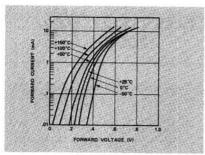


Figure 15. Typical Variation of Forward Current (IF) vs. Forward Voltage (VF) at Various Temperatures for the HSCH-1001.

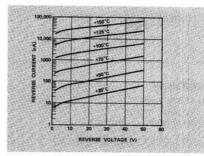


Figure 16. Typical Variation of Reverse Current (IR) vs. Reverse Voltage (VR) at Various Temperatures for the HSCH-1001.

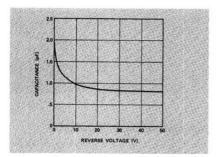


Figure 17. Typical Capacitance (C) vs. Reverse Voltage (VR) for the HSCH-1001.

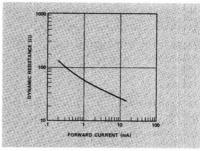


Figure 18. Typical Dynamic Resistance (R_D) vs. Forward Current (I_F) at T_A = 25° C for the HSCH-1001.

Mechanical Specifications

Lead Material: Lead Finish:

Maximum Soldering Temperature: Minimum Lead Strength: Typical Package Inductance:

Typical Package Capacitance:

Outline 15

Dumet 2800 Series: Tin 2300, 2900 Series: Gold 230° C for 5 sec. 4 lb. Pull

2800 Series: 2.0 nH 2300, 2900 Series: 3.0 nH 2800 Series: 0.2 pF 2300, 2900 Series: 0.07 pF

The leads on the Outline 15 package should be restricted so that the bend starts at least 1/16 inch from the glass body.

Outline 12 (DO-35)

Dumet Tin

260°C for 10 sec. 10 lb. Pull

1.8 nH

0.25 pF